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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Not For New Designs
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	100MHz
Connectivity	CANbus, I <sup>2</sup> C, LINbus, SCI, SPI, USB
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	30
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	32K x 8
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f5631mcdfl-v0">https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f5631mcdfl-v0</a>

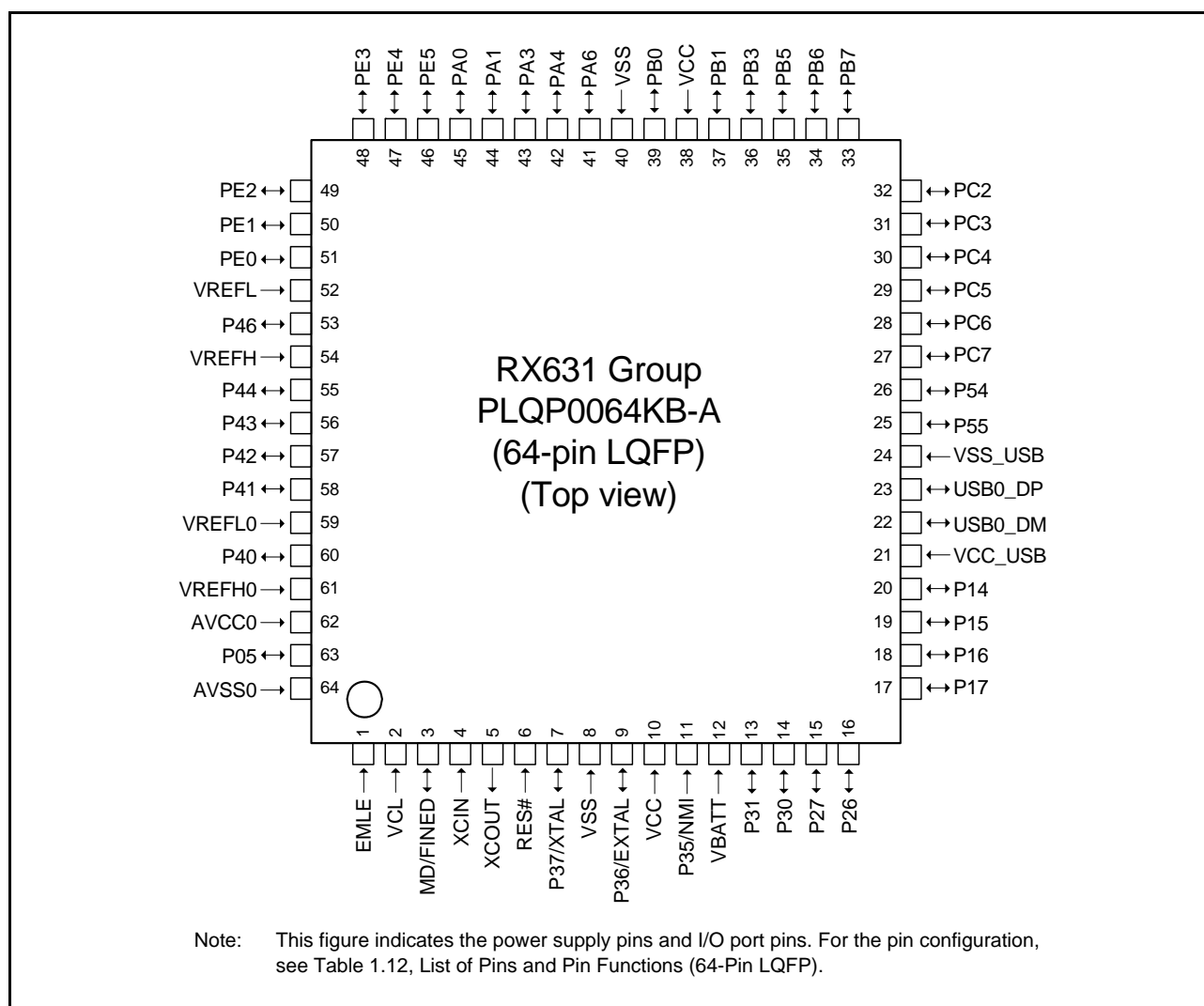


Figure 1.11 Pin Assignment (64-Pin LQFP)

**Table 1.6 List of Pin and Pin Functions (176-Pin LQFP) (2/5)**

Pin Number	Power Supply Clock System Control	I/O Port	Bus EXDMAC SDRAMC	Timer (MTU, TPU, TMR, PPG, RTC, POE)	Communications (ETHERC, SCIC, SCID, RSPI, RIIC, CAN, IEB, USB, and PDC)	Interrupt	S12AD, AD, DA
41	VSS						
42		P23	EDACK0	MTIOC3D/MTCLKD/ TIOCD3/PO3	TXD3/CTS0#/RTS0#/ SMOSI3/SS0#/SSDA3/ USB0_DPUPE/PIXD7		
43		P22	EDREQ0	MTIOC3B/MTCLKC/ TIOCC3/TMO0/PO2	SCK0/USB0_DRPD/ PIXD6		
44		P21		MTIOC1B/TIOCA3/ TMC10/PO1	RXD0/SMISO0/SSCL0/ SCL1/USB0_EXICEN/ PIXD5	IRQ9	
45		P20		MTIOC1A/TIOCB3/ TMR10/PO0	TXD0/SMOSI0/SSDA0/ SDA1/USB0_ID/PIXD4	IRQ8	
46		P17		MTIOC3A/MTIOC3B/ TIOCB0/TCLKD/TMO1/ PO15/POE8#	SCK1/TXD3/SMOSI3/ SSDA3/MISOA/SDA2-DS/ IETXD/USB1_VBUS/ PIXD3	IRQ7	ADTRG#
47		P87		TIOCA2	PIXD2		
48		P16		MTIOC3C/MTIOC3D/ TIOCB1/TCLKC/TMO2/ PO14/RTCCOUT	TXD1/RXD3/SMOSI1/ SMISO3/SSDA1/SSCL3/ MOSIA/SCL2-DS/IERXD/ USB0_VBUS/ USB0_VBUSEN/ USB0_OVRCURB	IRQ6	ADTRG0#
49		P86		TIOCA0	PIXD1		
50		P15		MTIOC0B/MTCLKB/ TIOCB2/TCLKB/TMC12/ PO13	RXD1/SCK3/SMISO1/ SSCL1/CRX1-DS/ USB1_DPUPE/PIXD0	IRQ5	
51		P14		MTIOC3A/MTCLKA/ TIOCB5/TCLKA/TMR12/ PO15	CTS1#/RTS1#/SS1#/ CTX1/USB0_DPUPE/ USB0_OVRCURA	IRQ4	
52		P85					
53		P13		MTIOC0B/TIOCA5/TMO3/ PO13	TXD2/SMOSI2/SSDA2/ SDA0[FM+]	IRQ3	ADTRG#
54		P12		MTIC5U/TMC11	RXD2/SMISO2/SSCL2/ SCL0[FM+]	IRQ2	
55		P11		MTIC5V/TMC13	SCK2	IRQ1	
56		P10		MTIC5W/TMR13		IRQ0	
57	VCC_USB						
58					USB0_DM		
59					USB0_DP		
60	VSS_USB						
61		P57	WAIT#/WR3#/ BC3#/EDREQ1				
62		P56	WR2#/BC2#/ EDACK1	MTIOC3C/TIOCA1			
63					USB1_DM		
64					USB1_DP		
65	VCC_USB						
66		P55	WAIT#/ EDREQ0	MTIOC4D/TMO3	ET_EXOUT/CRX1	IRQ10	
67		P54	ALE/EDACK0	MTIOC4B/TMC11	ET_LINKSTA/CTS2#/ RTS2#/SS2#/CTX1		
68		P53*1	BCLK				
69		P84					
70		P52	RD#		RXD2/SMISO2/SSCL2/ SSLB3		
71		P51	WR1#/BC1#/ WAIT#		SCK2/SSLB2		

**Table 1.7 List of Pins and Pin Functions (145-Pin TFLGA) (2/5)**

Pin No. 145-pin TFLGA	Power Supply Clock System Control	I/O Port	Bus EXDMAC SDRAMC	Timers (MTU, TPU, TMR, PPG, RTC, POE)	Communications (ETHERC, SC1c, SC1d, RSPI, RIIC, CAN, IEB, USB, and PDC)	Interrupt	S12AD AD DA
D5	VCC						
D6		P93	A19		CTS7#/RTS7#/SS7#		AN017
D7		PD5	D5[A5/D5]	MTIC5W/POE2#	SSLC1	IRQ5	AN013
D8		P60	CS0#				
D9		P64	CS4#/WE#				
D10		PE7	D15[A15/D15]	TIOCB11	MISOB	IRQ7	AN5
D11	VCC						
D12		PE5	D13[A13/D13]	MTIOC4C/MTIOC2B/ TIOCB10	RSPCKB/ET_RX_CLK/ REF50CK	IRQ5	AN3
D13		PE6	D14[A14/D14]	TIOCA11	MOSIB	IRQ6	AN4
E1	VSS						
E2	VCL						
E3		PJ5					
E4	EMLE						
E5		P44				IRQ12-DS	AN004
E10		PA0	A0/BC0#	MTIOC4A/TIOCA0/ PO16	SSLA1/ET_TX_EN/ RMII_TXD_EN		
E11		P66	CS6#/DQM0		CTX2*2		
E12		P65	CS5#/CKE				
E13		P67	CS7#/DQM1		CRX2*2	IRQ15	
F1	XCIN						
F2	XCOUT						
F3		PJ3		MTIOC3C	CTS6#/RTS6#/CTS0#/ RTS0#/SS6#/SS0#		
F4	VBATT						
F10		PA3	A3	MTIOC0D/MTCLKD/ TIOC0D/TCLKB/PO19	RXD5/SMISO5/SSCL5/ ET_MDIO	IRQ6-DS	
F11	VSS						
F12		PA1	A1	MTIOC0B/MTCLKC/ TIOCB0/PO17	SCK5/SSLA2/ET_WOL	IRQ11	
F13		PA2	A2	PO18	RXD5/SMISO5/SSCL5/ SSLA3		
G1	XTAL	P37					
G2	RES#						
G3	MD/FINED						
G4	BSCANP						
G10		PA5	A5	TIOCB1/PO21	RSPCKA/ET_LINKSTA		
G11		PA6	A6	MTIC5V/MTCLKB/ TIOCA2/TMCI3/PO22/ POE2#	CTS5#/RTS5#/SS5# MOSIA/ET_EXOUT		
G12	VCC						
G13		PA4	A4	MTIC5U/MTCLKA/ TIOCA1/TMRI0/PO20	TXD5/SMOSI5/SSDA5/ SSLA0/ET_MDC	IRQ5-DS	
H1	EXTAL	P36					
H2	VCC						
H3	VSS						
H4		P35				NMI	
H10		P72	CS2#		ET_MDC		
H11		P71	CS1#		ET_MDIO		

## 2.3 Register Associated with DSP Instructions

### (1) Accumulator (ACC)

The accumulator (ACC) is a 64-bit register used for DSP instructions. The accumulator is also used for the multiply and multiply-and-accumulate instructions; EMUL, EMULU, FMUL, MUL, and RMPA, in which case the prior value in the accumulator is modified by execution of the instruction.

Use the MVTACHI and MVTACLO instructions for writing to the accumulator. The MVTACHI and MVTACLO instructions write data to the higher-order 32 bits (bits 63 to 32) and the lower-order 32 bits (bits 31 to 0), respectively.

Use the MVFACHI and MVFACMI instructions for reading data from the accumulator. The MVFACHI and MVFACMI instructions read data from the higher-order 32 bits (bits 63 to 32) and the middle 32 bits (bits 47 to 16), respectively.

## 4. I/O Registers

This section gives information on the on-chip I/O register addresses. The information is given as shown below. Notes on writing to registers are also given at the end.

### (1) I/O register addresses (address order)

- Registers are listed from the lower allocation addresses.
- Registers are classified according to module symbols.
- The number of access cycles indicates the number of cycles based on the specified reference clock.
- Among the internal I/O register area, addresses not listed in the list of registers are reserved. Reserved addresses must not be accessed. Do not access these addresses; otherwise, the operation when accessing these bits and subsequent operations cannot be guaranteed.

### (2) Notes on writing to I/O registers

When writing to an I/O register, the CPU starts executing the subsequent instruction before completing I/O register write. This may cause the subsequent instruction to be executed before the post-update I/O register value is reflected on the operation.

As described in the following examples, special care is required for the cases in which the subsequent instruction must be executed after the post-update I/O register value is actually reflected.

#### [Examples of cases requiring special care]

- The subsequent instruction must be executed while an interrupt request is disabled with the IENj bit in IERN of the ICU (interrupt request enable bit) cleared to 0.
- A WAIT instruction is executed immediately after the preprocessing for causing a transition to the low power consumption state.

In the above cases, after writing to an I/O register, wait until the write operation is completed using the following procedure and then execute the subsequent instruction.

- Write to an I/O register.
- Read the value from the I/O register to a general register.
- Execute the operation using the value read.
- Execute the subsequent instruction.

#### [Instruction examples]

- Byte-size I/O registers

```
MOV.L #SFR_ADDR, R1
MOV.B #SFR_DATA, [R1]
CMP [R1].UB, R1
;; Next process
```

- Word-size I/O registers

```
MOV.L #SFR_ADDR, R1
MOV.W #SFR_DATA, [R1]
CMP [R1].W, R1
;; Next process
```

**Table 4.1 List of I/O Registers (Address Order) (40/50)**

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States		Related Function
						ICLK≥PCLK	ICLK<PCLK	
000A 0054h	USB0	USB request type register	USBREQ	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0056h	USB0	USB request value register	USBVAL	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0058h	USB0	USB request index register	USBINDX	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 005Ah	USB0	USB request length register	USBLENG	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 005Ch	USB0	DCP configuration register	DCPCFG	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 005Eh	USB0	DCP maximum packet size register	DCPMAXP	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0060h	USB0	DCP control register	DCPCTR	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0064h	USB0	Pipe window select register	PIPESEL	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	USBa
000A 0068h	USB0	Pipe configuration register	PIPECFG	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 006Ch	USB0	Pipe maximum packet size register	PIPEMAXP	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	

**Table 4.1 List of I/O Registers (Address Order) (45/50)**

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States		Related Function
						ICLK≥PCLK	ICLK<PCLK	
000A 024Eh	USB1	Device state changing register	DVCHGR	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0250h	USB1	USB address register	USBADDR	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0254h	USB1	USB request type register	USBREQ	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0256h	USB1	USB request value register	USBVAL	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0258h	USB1	USB request index register	USBINDX	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 025Ah	USB1	USB request length register	USBLENG	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	USBa
000A 025Ch	USB1	DCP configuration register	DCPCFG	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 025Eh	USB1	DCP maximum packet size register	DCPMAXP	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0260h	USB1	DCP control register	DCPCTR	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0264h	USB1	Pipe window select register	PIPESEL	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	



**Table 4.1 List of I/O Registers (Address Order) (47/50)**

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States		Related Function
						ICLK≥PCLK	ICLK<PCLK	
000A 027Eh	USB1	Pipe 8 control register	PIPE8CTR	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0280h	USB1	Pipe 9 control register	PIPE9CTR	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	USBa
000A 0290h	USB1	Pipe 1 transaction counter enable register	PIPE1TRE	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0292h	USB1	Pipe 1 transaction counter register	PIPE1TRN	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0294h	USB1	Pipe 2 transaction counter enable register	PIPE2TRE	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0296h	USB1	Pipe 2 transaction counter register	PIPE2TRN	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0298h	USB1	Pipe 3 transaction counter enable register	PIPE3TRE	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 029Ah	USB1	Pipe 3 transaction counter register	PIPE3TRN	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 029Ch	USB1	Pipe 4 transaction counter enable register	PIPE4TRE	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 029Eh	USB1	Pipe 4 transaction counter register	PIPE4TRN	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	USBa

**Table 4.1 List of I/O Registers (Address Order) (48/50)**

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States		Related Function
						ICLK≥PCLK	ICLK<PCLK	
000A 02A0h	USB1	Pipe 5 transaction counter enable register	PIPE5TRE	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 02A2h	USB1	Pipe 5 transaction counter register	PIPE5TRN	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0400h	USB	Deep standby USB transceiver control/pin monitor register	DPUSR0R	32	32	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0404h	USB	Deep standby USB suspend/resume interrupt register	DPUSR1R	32	32	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9/ (frequency ratio of ICLK/ PCLKB) <sup>16</sup>	
000A 0500h	PDC	PDC Control Register 0	PCCR0	32	32	2, 3PCLKA	2 ICLK	PDC
000A 0504h	PDC	PDC Control Register 1	PCCR1	32	32	2, 3PCLKA	2 ICLK	
000A 0508h	PDC	PDC Status Register	PCSR	32	32	2, 3PCLKA	2 ICLK	
000A 050Ch	PDC	PDC Pin Monitor Register	PCMONR	32	32	2, 3PCLKA	2 ICLK	
000A 0510h	PDC	PDC Receive Data Register	PCDR	32	32	2, 3PCLKA	2 ICLK	
000A 0514h	PDC	Vertical Capture Register	VCR	32	32	2, 3PCLKA	2 ICLK	
000A 0518h	PDC	Horizontal Capture Register	HCR	32	32	2, 3PCLKA	2 ICLK	
000C 0000h	EDMAC	EDMAC mode register	EDMR	32	32	5, 6 PCLKA	—	EDMAC
000C 0008h	EDMAC	EDMAC transmit request register	EDTRR	32	32	5, 6 PCLKA	—	
000C 0010h	EDMAC	EDMAC receive request register	EDRRR	32	32	5, 6 PCLKA	—	
000C 0018h	EDMAC	Transmit descriptor list start address register	TDLAR	32	32	5, 6 PCLKA	—	
000C 0020h	EDMAC	Receive descriptor list start address register	RDLAR	32	32	5, 6 PCLKA	—	
000C 0028h	EDMAC	ETHERC/EDMAC status register	EESR	32	32	5, 6 PCLKA	—	
000C 0030h	EDMAC	ETHERC/EDMAC status interrupt permission register	EESIPR	32	32	5, 6 PCLKA	—	
000C 0038h	EDMAC	Transmit/receive status copy enable register	TRSCER	32	32	5, 6 PCLKA	—	
000C 0040h	EDMAC	Receive missed-frame counter register	RMFCR	32	32	5, 6 PCLKA	—	
000C 0048h	EDMAC	Transmit FIFO threshold register	TFTR	32	32	5, 6 PCLKA	—	
000C 0050h	EDMAC	FIFO depth register	FDR	32	32	5, 6 PCLKA	—	
000C 0058h	EDMAC	Receiving method control register	RMCR	32	32	5, 6 PCLKA	—	
000C 0064h	EDMAC	Transmit FIFO underrun counter	TFUCR	32	32	5, 6 PCLKA	—	
000C 0068h	EDMAC	Receive FIFO overflow counter	RFOCR	32	32	5, 6 PCLKA	—	
000C 006Ch	EDMAC	Independent output signal setting register	IOSR	32	32	5, 6 PCLKA	—	EDMAC
000C 0070h	EDMAC	Flow control start FIFO threshold setting register	FCFTR	32	32	5, 6 PCLKA	—	
000C 0078h	EDMAC	Receive data padding insert register	RPADIR	32	32	5, 6 PCLKA	—	
000C 007Ch	EDMAC	Transmit interrupt setting register	TRIMD	32	32	5, 6 PCLKA	—	
000C 00C8h	EDMAC	Receive buffer write address register	RBWAR	32	32	5, 6 PCLKA	—	
000C 00CCh	EDMAC	Receive descriptor fetch address register	RDFAR	32	32	5, 6 PCLKA	—	
000C 00D4h	EDMAC	Transmit buffer read address register	TBRAR	32	32	5, 6 PCLKA	—	
000C 00D8h	EDMAC	Transmit descriptor fetch address register	TDFAR	32	32	5, 6 PCLKA	—	

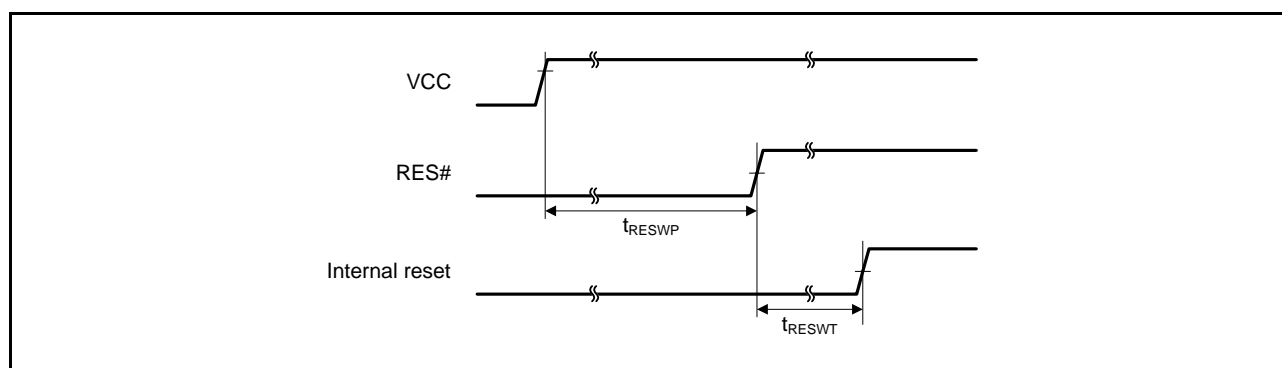
**Table 4.1 List of I/O Registers (Address Order) (49/50)**

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States		Related Function
						ICLK≥PCLK	ICLK<PCLK	
000C 0100h	ETHERC	ETHERC mode register	ECMR	32	32	5, 6 PCLKA	—	ETHERC
000C 0108h	ETHERC	Receive frame length register	RFLR	32	32	5, 6 PCLKA	—	
000C 0110h	ETHERC	ETHERC status register	ECSR	32	32	5, 6 PCLKA	—	
000C 0118h	ETHERC	ETHERC interrupt permission register	ECSIPR	32	32	5, 6 PCLKA	—	
000C 0120h	ETHERC	PHY interface register	PIR	32	32	5, 6 PCLKA	—	
000C 0128h	ETHERC	PHY status register	PSR	32	32	5, 6 PCLKA	—	
000C 0140h	ETHERC	Random number generation counter upper limit setting register	RDMLR	32	32	5, 6 PCLKA	—	
000C 0150h	ETHERC	IPG register	IPGR	32	32	5, 6 PCLKA	—	
000C 0154h	ETHERC	Automatic PAUSE frame register	APR	32	32	5, 6 PCLKA	—	
000C 0158h	ETHERC	Manual PAUSE frame register	MPR	32	32	5, 6 PCLKA	—	
000C 0160h	ETHERC	PAUSE Frame receive counter register	RFCF	32	32	5, 6 PCLKA	—	
000C 0164h	ETHERC	Automatic PAUSE frame retransmit count register	TPAUSER	32	32	5, 6 PCLKA	—	
000C 0168h	ETHERC	PAUSE frame retransmit counter register	TPAUSECR	32	32	5, 6 PCLKA	—	
000C 016Ch	ETHERC	Broadcast frame receive count setting register	BCFR	32	32	5, 6 PCLKA	—	
000C 01C0h	ETHERC	MAC address high register	MAHR	32	32	5, 6 PCLKA	—	
000C 01C8h	ETHERC	MAC address low register	MALR	32	32	5, 6 PCLKA	—	
000C 01D0h	ETHERC	Transmit retry over counter register	TROCR	32	32	5, 6 PCLKA	—	
000C 01D4h	ETHERC	Delayed collision detect counter register	CDCR	32	32	5, 6 PCLKA	—	
000C 01D8h	ETHERC	Lost carrier counter register	LCCR	32	32	5, 6 PCLKA	—	
000C 01DCh	ETHERC	Carrier not detect counter register	CNDCR	32	32	5, 6 PCLKA	—	
000C 01E4h	ETHERC	CRC error frame receive counter register	CEFCR	32	32	5, 6 PCLKA	—	
000C 01E8h	ETHERC	Frame receive error counter register	FRECR	32	32	5, 6 PCLKA	—	
000C 01ECh	ETHERC	Too-short frame receive counter register	TSFRCR	32	32	5, 6 PCLKA	—	
000C 01F0h	ETHERC	Too-long frame receive counter register	TLFRCR	32	32	5, 6 PCLKA	—	
000C 01F4h	ETHERC	Residual-bit frame receive counter register	RFCR	32	32	5, 6 PCLKA	—	
000C 01F8h	ETHERC	Multicast address frame receive counter register	MAFCR	32	32	5, 6 PCLKA	—	

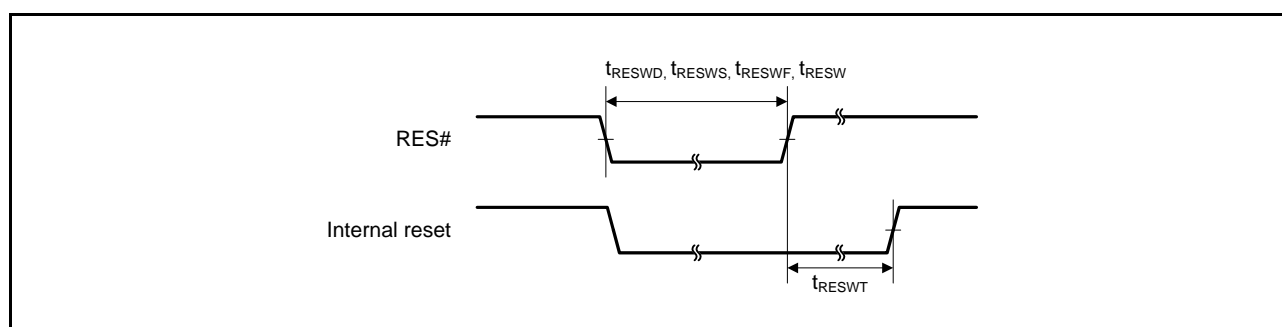
**Table 5.5 DC Characteristics (4) (for G Version (+85 < Ta ≤ +105°C))**

Conditions: VCC = AVCC0 = VREFH = VCC\_USB = V<sub>BATT</sub> = 2.7 to 3.6 V, VREFH0 = 2.7 V to AVCC0,  
VSS = AVSS0 = VREFL/VREFL0 = VSS\_USB = 0 V, T<sub>a</sub> = T<sub>opr</sub>

Item			Symbol	Min.	Typ.	Max.	Unit	Test Conditions		
Supply current*1	High-speed operating mode	Max.*2		I <sub>CC</sub> *3	—	—	115	mA	ICLK = 100 MHz PCLKA = 100MHz PCLKB = 50 MHz FCLK = 50 MHz BCLK = 100MHz	
		Normal*4	Peripheral function: clock signal supplied*4		—	52	—			
			Peripheral function: clock signal stopped*4		—	40	—			
		Sleep mode			—	25	80			
		All-module-clock-stop mode (reference value)			—	20	53			
		Increased by BGO operation*5			—	15	—			
	Low-speed operating mode 1*6		—		4	—	ICLK = 1 MHz			
	Low-speed operating mode 2		—		1	—	ICLK = 32.768 kHz			
	Software standby mode		—		0.2	9				
	Deep software standby mode	Power supplied to RAM and USB resume detecting unit			—	22	200	μA		
		Power not supplied to RAM and USB resume detecting unit	Power-on reset circuit and low-power consumption function disabled		—	21	60			
			Power-on reset circuit and low-power consumption function enabled		—	6.2	28			
		Increase when the RTC is operating	When a crystal oscillator for low clock loads is in use		—	1.0	—			
			When a crystal oscillator for standard clock loads is in use		—	3.0	—			
		RTC operating while VCC is off (with the battery backup function, only the RTC and sub-clock oscillator operate)	When a crystal oscillator for low clock loads is in use		—	0.9	—		V <sub>BATT</sub> = 2.0 V, VCC = 0V	
			When a crystal oscillator for standard clock loads is in use		—	1.6	—		V <sub>BATT</sub> = 3.3 V, VCC = 0V	
						—	1.7		—	V <sub>BATT</sub> = 2.0 V(for products with 100 pins or more), VBATT = 2.3 V (for the 64-pin product), VCC = 0V
					—	3.3	—		V <sub>BATT</sub> = 3.3 V, VCC = 0V	
Analog power supply current*7	During 12-bit A/D conversion (including temperature sensor)		I <sub>AVCC0</sub>	—	2.3	3.2	mA			
	During 10-bit A/D conversion		I <sub>VREFH</sub> *9	—	1.0	1.65				
	During D/A conversion (per unit)			—	0.7	1.0				
	Waiting for A/D, D/A conversion (all units)*10		—	—	25	35		μA		
	A/D, D/A converter in standby mode (all units)*10			—	0.1	5		μA		
Reference power supply current	During 12-bit A/D conversion		I <sub>VREFH0</sub>	—	0.6	0.7	mA			
	Waiting for 12-bit A/D conversion (per unit)			—	0.5	0.6				
	12-bit A/D converter in standby mode (per unit)			—	0.1	2.0		μA		
RAM standby voltage			V <sub>RAM</sub>	2.7	—	—	V			
VCC rising gradient			SrVCC	8.4	—	20000	μs/V			
VCC falling gradient*8			SfVCC	8.4	—	—	μs/V			



**Figure 5.1** Reset Input Timing at Power-On



**Figure 5.2** Reset Input Timing

- Note 1. This is the time until the clock is used after setting P36 and P37 as inputs, and then clearing the main clock oscillator stop bit (MOSCCR.MOSTP) to 0 (selecting operation).
- Note 2. This is the time until the frequency of oscillation by the HOCO (fHOCO) reaches the range for guaranteed operation after release from the reset state.
- Note 3. When using a main clock, ask the manufacturer of the oscillator to evaluate its oscillation. Refer to the results of evaluation provided by the manufacturer for the oscillation stabilization time.
- Note 4. The number of cycles n selected by the value of the MOSCWTCR.MSTS[4:0] bits determines the main-clock oscillation stabilization waiting time in accord with the formula below.

$$t_{\text{MAINOSCWT}} = t_{\text{MAINOSC}} + \frac{n + 16384}{f_{\text{MAIN}}}$$

- Note 5. The number of cycles n selected by the value of the PLLWTCR.PSTS[4:0] bits determines the PLL-clock oscillation stabilization waiting time in accord with the formula below.

$$t_{\text{PLLWT1}} = t_{\text{PLL1}} + \frac{n + 131072}{f_{\text{PLL}}}$$

$$t_{\text{PLLWT2}} = t_{\text{PLL2}} + \frac{n + 131072}{f_{\text{PLL}}} = t_{\text{MAINOSC}} + t_{\text{PLL1}} + \frac{n + 131072}{f_{\text{PLL}}}$$

**Table 5.17 Bus Timing (packages with 100 pins or less)**

Conditions:  $V_{CC} = AVCC0 = VREFH = VCC\_USB = 2.7$  to  $3.6$  V,  $VREFH0 = 2.7$  V to  $AVCC0$ ,

$VSS = AVSS0 = VREFL/VREFL0 = VSS\_USB = 0$  V,

$ICLK = 8$  to  $100$  MHz,  $BCLK$  pin =  $8$  to  $50$  MHz,  $T_a = T_{opr}$

Output load conditions:  $V_{OH} = VCC \times 0.5$ ,  $V_{OL} = VCC \times 0.5$ ,  $I_{OH} = -1.0$  mA,  $I_{OL} = 1.0$  mA,  $C = 30$  pF

High drive output is selected by the drive capacity control register.

Item	Symbol	Min.	Max.	Unit	Test Conditions
Address delay time	$t_{AD}$	—	20	ns	Figure 5.17 to Figure 5.22
Byte control delay time	$t_{BCD}$	—	20	ns	
CS# delay time	$t_{CSD}$	—	20	ns	
ALE delay time	$t_{ALED}$	—	20	ns	
RD# delay time	$t_{RSD}$	—	20	ns	
Read data setup time	$t_{RDS}$	15	—	ns	
Read data hold time	$t_{RDH}$	0	—	ns	
WR# delay time	$t_{WRD}$	—	20	ns	
Write data delay time	$t_{WDD}$	—	20	ns	
Write data hold time	$t_{WDH}$	0	—	ns	
WAIT# setup time	$t_{WTS}$	15	—	ns	Figure 5.23
WAIT# hold time	$t_{WTH}$	0	—	ns	

**Table 5.23 Timing of On-Chip Peripheral Modules (5)**

Conditions: VCC = AVCC0 = VREFH = VCC\_USB = 2.7 to 3.6 V, VREFH0 = 2.7 V to AVCC0

VSS = AVSS0 = VREFL/VREFL0 = VSS\_USB = 0 V

PCLK = 8 to 50 MHz

 $T_a = T_{opr}$ 

High drive output is selected by the drive capacity control register.

Item		Symbol	Min.*1,*2	Max.*	Unit	Test Conditions
RIIC (Standard-mode, SMBus) ICFER.FMPE = 0	SCL input cycle time	$t_{SCL}$	$6(12) \times t_{IICcyc} + 1300$	—	ns	Figure 5.47
	SCL input high pulse width	$t_{SCLH}$	$3(6) \times t_{IICcyc} + 300$	—	ns	
	SCL input low pulse width	$t_{SCLL}$	$3(6) \times t_{IICcyc} + 300$	—	ns	
	SCL, SDA input rise time	$t_{Sr}$	—	1000	ns	
	SCL, SDA input fall time	$t_{Sf}$	—	300	ns	
	SCL, SDA input spike pulse removal time	$t_{SP}$	0	$1(4) \times t_{IICcyc}$	ns	
	SDA input bus free time	$t_{BUF}$	$3(6) \times t_{IICcyc} + 300$	—	ns	
	Start condition input hold time	$t_{STAH}$	$t_{IICcyc} + 300$	—	ns	
	Restart condition input setup time	$t_{STAS}$	1000	—	ns	
	Stop condition input setup time	$t_{STOS}$	1000	—	ns	
	Data input setup time	$t_{SDAS}$	$t_{IICcyc} + 50$	—	ns	
	Data input hold time	$t_{SDAH}$	0	—	ns	
	SCL, SDA capacitive load	$C_b$	—	400	pF	
RIIC (Fast-mode)	SCL input cycle time	$t_{SCL}$	$6(12) \times t_{IICcyc} + 600$	—	ns	
	SCL input high pulse width	$t_{SCLH}$	$3(6) \times t_{IICcyc} + 300$	—	ns	
	SCL input low pulse width	$t_{SCLL}$	$3(6) \times t_{IICcyc} + 300$	—	ns	
	SCL, SDA input rise time	$t_{Sr}$	$20 + 0.1C_b$	300	ns	
	SCL, SDA input fall time	$t_{Sf}$	$20 + 0.1C_b$	300	ns	
	SCL, SDA input spike pulse removal time	$t_{SP}$	0	$1(4) \times t_{IICcyc}$	ns	
	SDA input bus free time	$t_{BUF}$	$3(6) \times t_{IICcyc} + 300$	—	ns	
	Start condition input hold time	$t_{STAH}$	$t_{IICcyc} + 300$	—	ns	
	Restart condition input setup time	$t_{STAS}$	300	—	ns	
	Stop condition input setup time	$t_{STOS}$	300	—	ns	
	Data input setup time	$t_{SDAS}$	$t_{IICcyc} + 50$	—	ns	
	Data input hold time	$t_{SDAH}$	0	—	ns	
	SCL, SDA capacitive load	$C_b$	—	400	pF	

Note:  $t_{IICcyc}$ : RIIC internal reference clock (IIC $\phi$ ) Cycle

Note 1. The value within parentheses is applicable when the value of the ICMR3.NF[1:0] bits is 11b while the digital filter is enabled by the setting ICFER.NFE = 1.

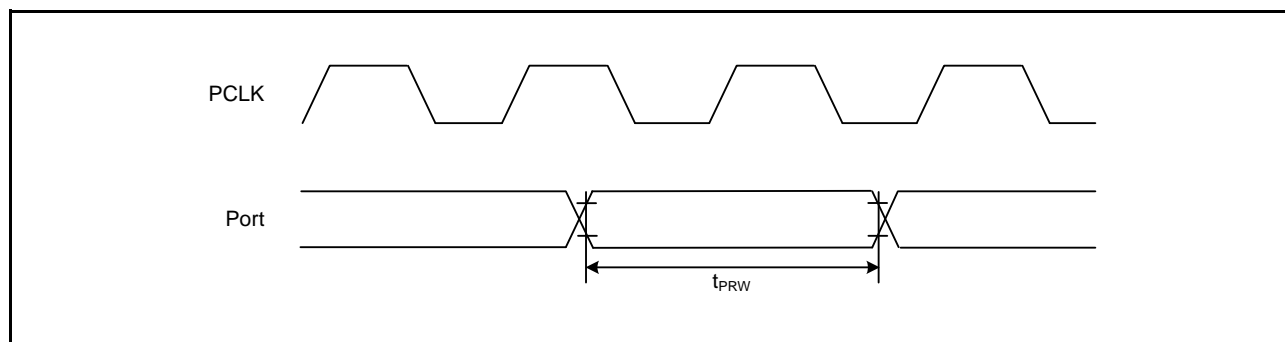
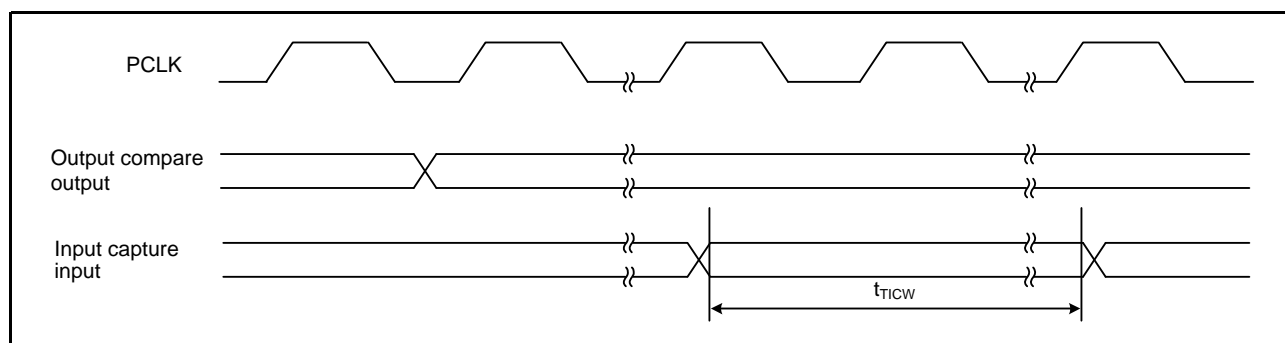
Note 2.  $C_b$  is the total capacitance of the bus lines.

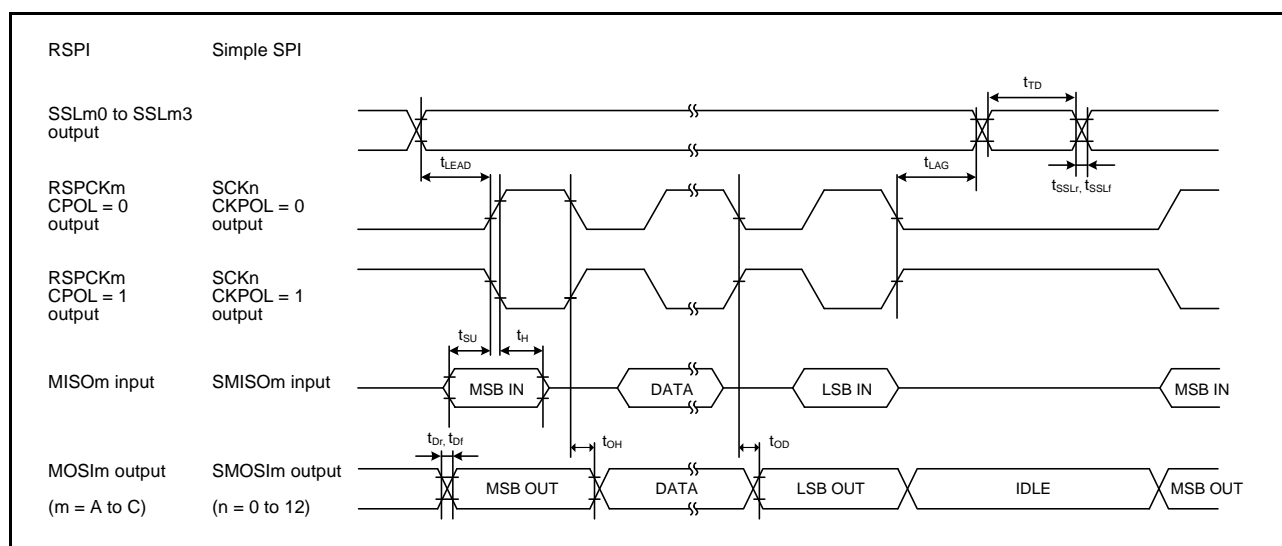


**Table 5.26 Timing of On-Chip Peripheral Modules (8)**

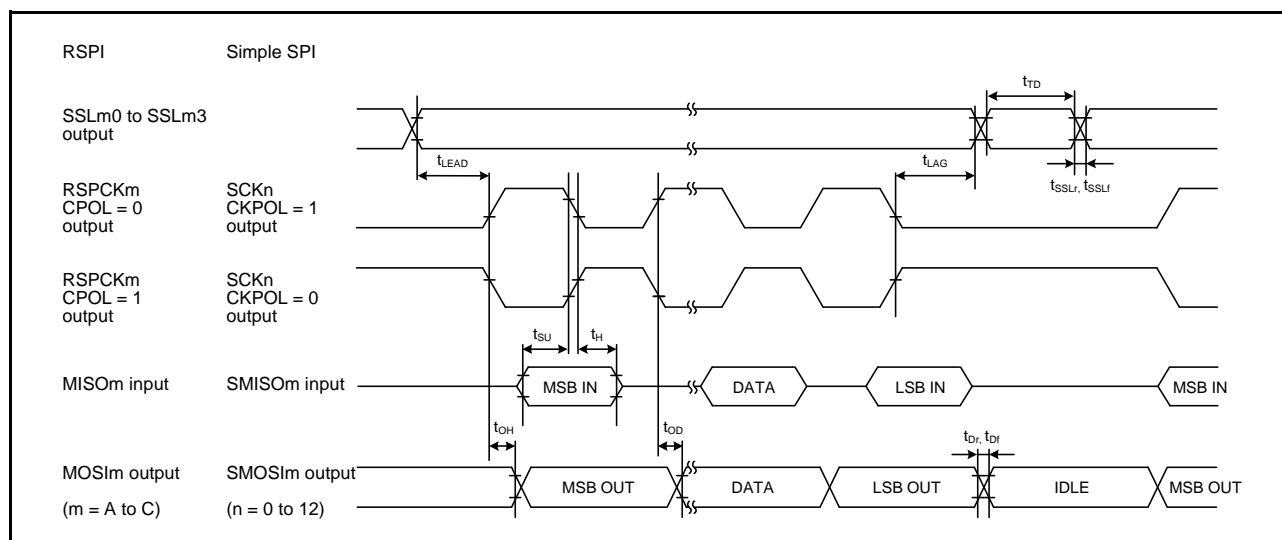
Conditions: VCC = AVCC0 = VREFH = VCC\_USB = 2.7 to 3.6V, VREFH0 = 2.7V to AVCC0,  
VSS = AVSS0 = VREFL/VREFL0 = VSS\_USB = 0V, PIXCLK = 27MHz, T<sub>a</sub> = T<sub>opr</sub>

	Item	Symbol	min	typ	max	Unit	Test Conditions
PDC	VSXNC/HSXNC input setup time	t <sub>SYNCSXNCSETUP</sub>	10	—	—	ns	Figure 5.58
	VSXNC/HSXNC input hold time	t <sub>SYNCSXNCHOLD</sub>	5	—	—	ns	
	PIXD input setup time	t <sub>DATASXNCSETUP</sub>	10	—	—	ns	
	PIXD input hold time	t <sub>DATASXNCHOLD</sub>	5	—	—	ns	
	PIXCLK input cycle time	t <sub>PIXcyc</sub>	37	—	1000	ns	Figure 5.59
	PIXCLK input pulse width high level	t <sub>PIXH</sub>	10	—	—	ns	
	PIXCLK input pulse width low level	t <sub>PIXL</sub>	10	—	—	ns	
	PCKO pin output cycle time	t <sub>PCKcyc</sub>	40	—	1000	ns	Figure 5.60
	PCKO pin output high level pulse width	t <sub>PCKH</sub>	13	—	—	ns	
	PCKO pin output low level pulse width	t <sub>PCKL</sub>	13	—	—	ns	
	PCKO pin output rising time	t <sub>PCKr</sub>	—	—	5	ns	
	PCKO pin output falling time	t <sub>PCKf</sub>	—	—	5	ns	

**Figure 5.34 I/O Port Input Timing****Figure 5.35 MTU Input/Output Timing**



**Figure 5.43 RSPI Timing (Master, CPHA = 0) and Simple SPI Timing (Master, CKPH = 1)**



**Figure 5.44 RSPI Timing (Master, CPHA = 1) and Simple SPI Timing (Master, CKPH = 0)**

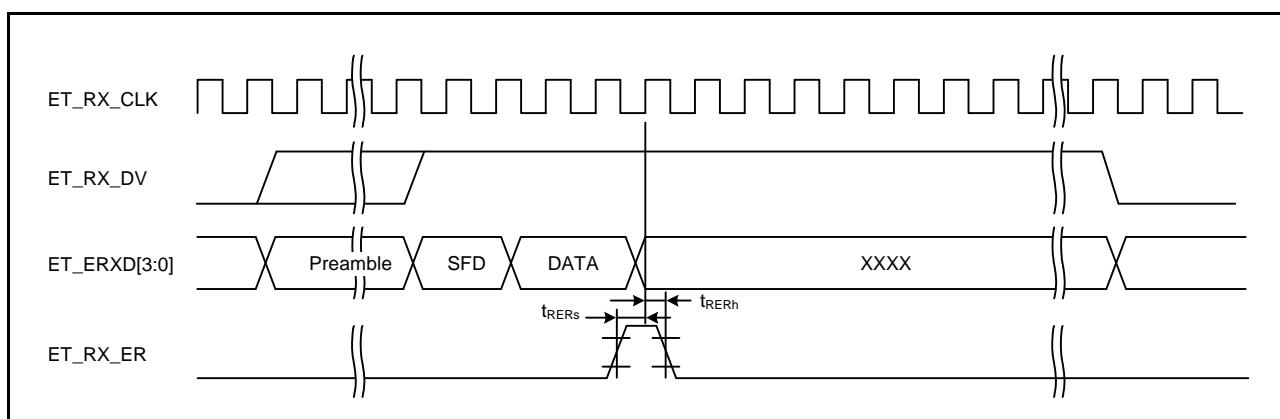


Figure 5.56 MII Reception Timing (Error Occurrence)

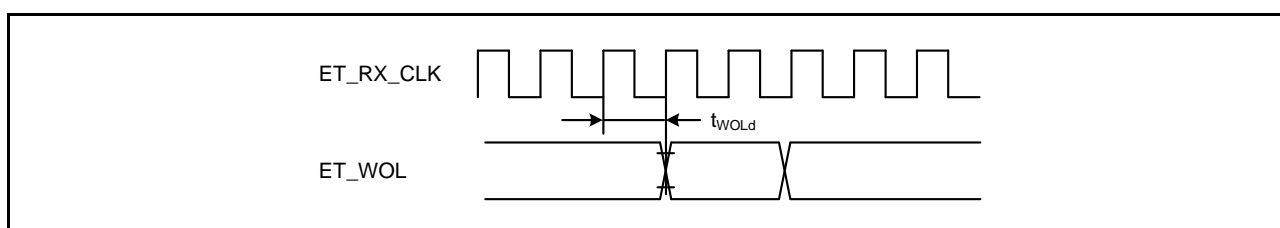


Figure 5.57 WOL Output Timing (MII)

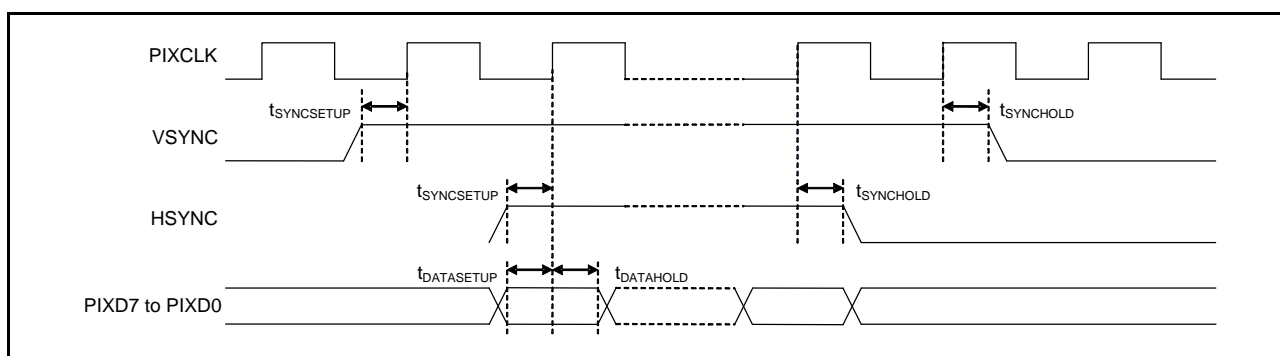


Figure 5.58 PDC Timing

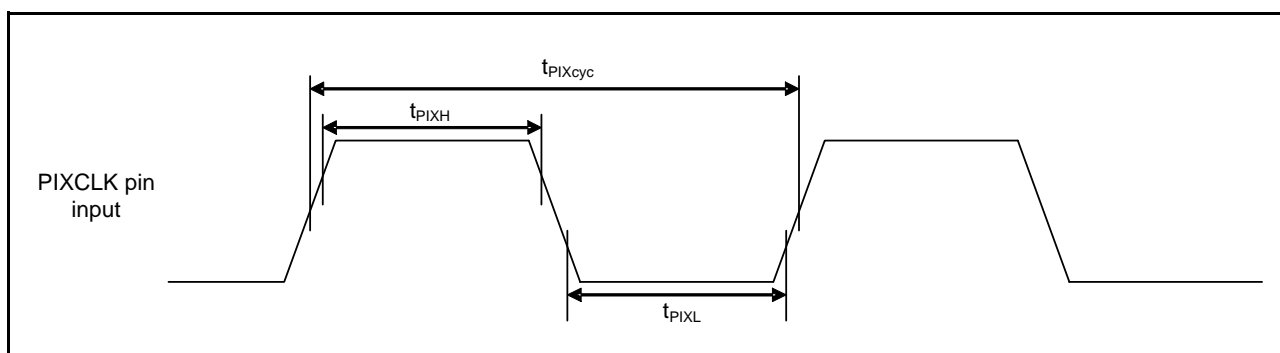


Figure 5.59 PDC Input Clock Characteristic

REVISION HISTORY	RX63N Group, RX631 Group Datasheet
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Rev.	Date	Description	
		Page	Summary
0.50	May 13, 2011	—	First Edition issued
0.90	Dec 27, 2011	All	<p>— Package added (177-pin TFLGA, 176-pin LFBGA, 145-pin TFLGA), module name changed</p> <p>— Interrupt Controller (ICUb) module name changed</p> <p>1. Overview</p> <p>2 to 6 Table 1.1 Outline of Specifications, Reset, Realtime clock, Temperature sensor, Power supply voltage, changed</p> <p>8 to 10 Table 1.3 List of Products, changed</p> <p>10 Figure 1.1 How to Read the Product Part No., changed</p> <p>12 to 17 Table 1.4 Pin Functions, BSCANP pin added</p> <p>18 Figure 1.3 Pin Assignment (176-Pin TFLGA), added</p> <p>19 Figure 1.4 Pin Assignment (176-Pin LFBGA), added</p> <p>20 Figure 1.5 Pin Assignment (176-Pin LQFP), pin 18 changed</p> <p>21 Figure 1.6 Pin Assignment (144-Pin TFLGA), added</p> <p>22 Figure 1.7 Pin Assignment (144-Pin LQFP), pin 16 changed</p> <p>23 Figure 1.8 Pin Assignment (100-Pin LQFP), pin 7 changed</p> <p>24 to 28 Table 1.5 List of Pins and Pin Functions (177-pin TFLGA, 176-pin LFBGA), added</p> <p>34 to 38 Table 1.7 List of Pins and Pin Functions (145-Pin TFLGA), added</p> <p>4. I/O Registers</p> <p>56 to 99 Table 5.1 List of I/O Registers, changed</p> <p>Appendix 2. Package Dimensions</p> <p>100 Figure A. 177-pin TFLGA (PTLG0177KA-A), added</p> <p>101 Figure B. 176-pin LFBGA (PLBG0176GA-A), added</p> <p>103 Figure D. 145-pin TFLGA (PTLG0145KA-A), added</p> <p>105 Figure F. 100-pin TFLGA (PTLG0100KA-A), added</p>
1.00	Jun 06, 2012	1. Overview	<p>2 to 6 Table 1.1 Outline of Specifications: CPU, ROM, RAM, E2 DataFlash, clock generation circuit, temperature sensor, power supply voltage, changed. Low power consumption, deleted</p> <p>8 to 10 Table 1.3 List of Products, changed</p> <p>11 Figure 1.2 Block Diagram, changed</p> <p>12 Table 1.4 Pin Functions, description of VCC, changed</p> <p>24 to 28 Table 1.5 List of Pin and Pin Functions (177-Pin TFLGA, 176-Pin LFBGA): SDRAMC, added to table header; BCLK in pin number line M8, moved to Power Supply Clock System Control column</p> <p>29 to 33 Table 1.6 List of Pin and Pin Functions (176-Pin LQFP): SDRAMC, added to table header; BCLK in pin number line 68, moved to Power Supply Clock System Control column</p> <p>34 to 38 Table 1.7 List of Pin and Pin Functions (145-Pin TFLGA): SDRAMC, added to table header; MOSIB, added to pin number line D13; T_ERXD1 in pin number line H12, changed to ET_ERXD1; PO8, added to pin number line J4; BCLK in pin number line K6, moved to Power Supply Clock System Control column</p> <p>39 to 43 Table 1.8 List of Pins and Pin Functions (144-Pin LQFP): SDRAMC, added to table header; PO8, added to pin number line 29; BCLK in pin number line 53, moved to Power Supply Clock System Control column; T_ERXD1 in pin number 87, changed to ET_ERXD1; MOSIB, added to pin number line 102</p> <p>44 to 47 Table 1.9 List of Pins and Pin Functions (100-Pin LQFP): BCLK in pin number line 41, moved to Power Supply Clock System Control column</p> <p>4. I/O Registers</p> <p>57, 58 Table 4.1, MPU registers, added</p> <p>5. Electrical Characteristics</p> <p>105 to 163 Added</p>

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